

3. (amended) The insulation film according to claim 1 wherein the insulation film comprises:

a plurality of circuit patterns formed two-dimensionally upon the insulation film according to size of the semiconductor package; and

a for-plating-electricity-supply-use conductor pattern electrically connected with the plurality of circuit patterns.

4. (amended) The insulation film according to claim 3 wherein the for-plating-electricity-supply-use conductor pattern comprises:

a main line surrounding a perimeter of the plurality of circuit patterns; and

a sub-line electrically connecting each of the circuit patterns to the main line.

REMARKS

If the Examiner has any questions, or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,



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